

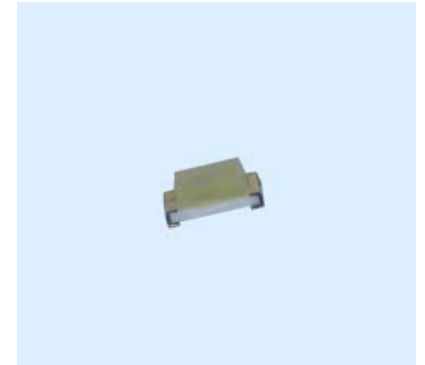
## Technical Data Sheet

### 0603 Package Chip LED (0.6 mm Height)

DW-0603-W

#### Features

- Package in 8mm tape on 13" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.
- Pb-free.
- The product itself will remain within RoHS complaint version.



#### Descriptions

- The SMD Taping is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

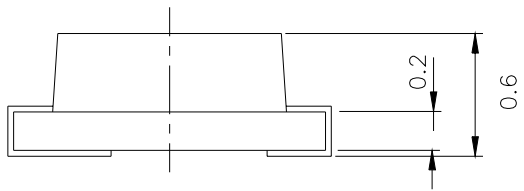
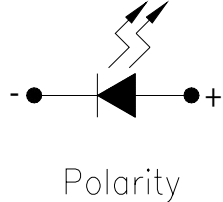
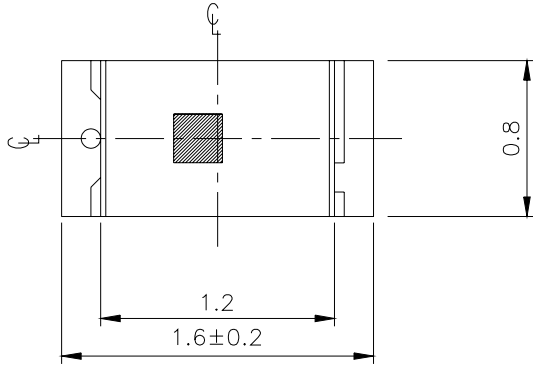
#### Applications

- Automotive: backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

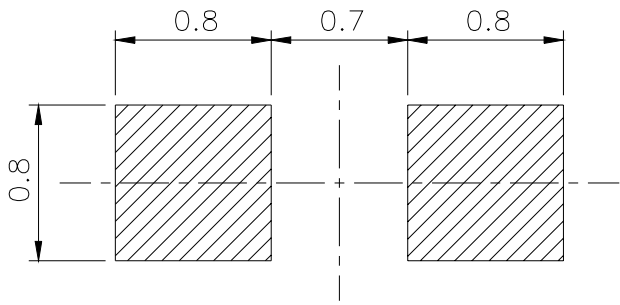
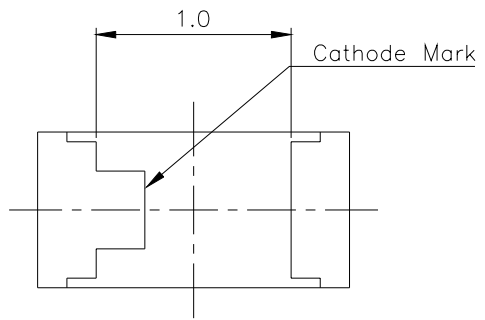
#### Device Selection Guide

Part No.	Chip		Lens Color
	Material	Emitted Color	
.....	InGaN	Pure White	Yellow Diffused

**Package Outline Dimensions**



For reflow soldering (Propose)



**Note:** The tolerances unless mentioned is  $\pm 0.1$ mm ,Unit = mm.

**Absolute Maximum Ratings (Ta=25°C)**

Parameter	Symbol	Rating	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	25	mA
Operating Temperature	T <sub>opr</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +90	°C
Power Dissipation	P <sub>d</sub>	110	mW
Electrostatic Discharge(HBM)	ESD	150	V
Peak Forward Current (Duty 1/10 @1KHz)	I <sub>F</sub>	100	mA
Soldering Temperature	T <sub>sol</sub>	Reflow Soldering : 260°C for 10sec. Hand Soldering : 350°C for 3 sec.	

**Electro-Optical Characteristics (Ta=25°C)**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I <sub>v</sub>	28.5	-----	72.0	mcd	I <sub>F</sub> =5mA
Viewing Angle	2θ 1/2	-----	130	-----	deg	
Forward Voltage	V <sub>F</sub>	2.70	-----	3.15	V	
Reverse Current	I <sub>R</sub>	-----	-----	50	μ A	V <sub>R</sub> =5V

**Bin Range Of Luminous Intensity**

Symbol	Bin Code	Min.	Max.	Unit	Condition
I <sub>v</sub>	N	28.0	45.0	mcd	I <sub>F</sub> =5mA
	P	45.0	72.0		

**Bin Range Of Luminous Voltage**

Group	Bin	Min	Max	Unit	Condition
H	15	2.70	2.85	V	I <sub>F</sub> =5mA
	16	2.85	3.00		
	17	3.00	3.15		

Notes:

- 1.Tolerance of Luminous Intensity ±10%
- 2.Tolerance of Forward Voltage ±0.05V

**Chromaticity Coordinates Specifications for Bin Grading**

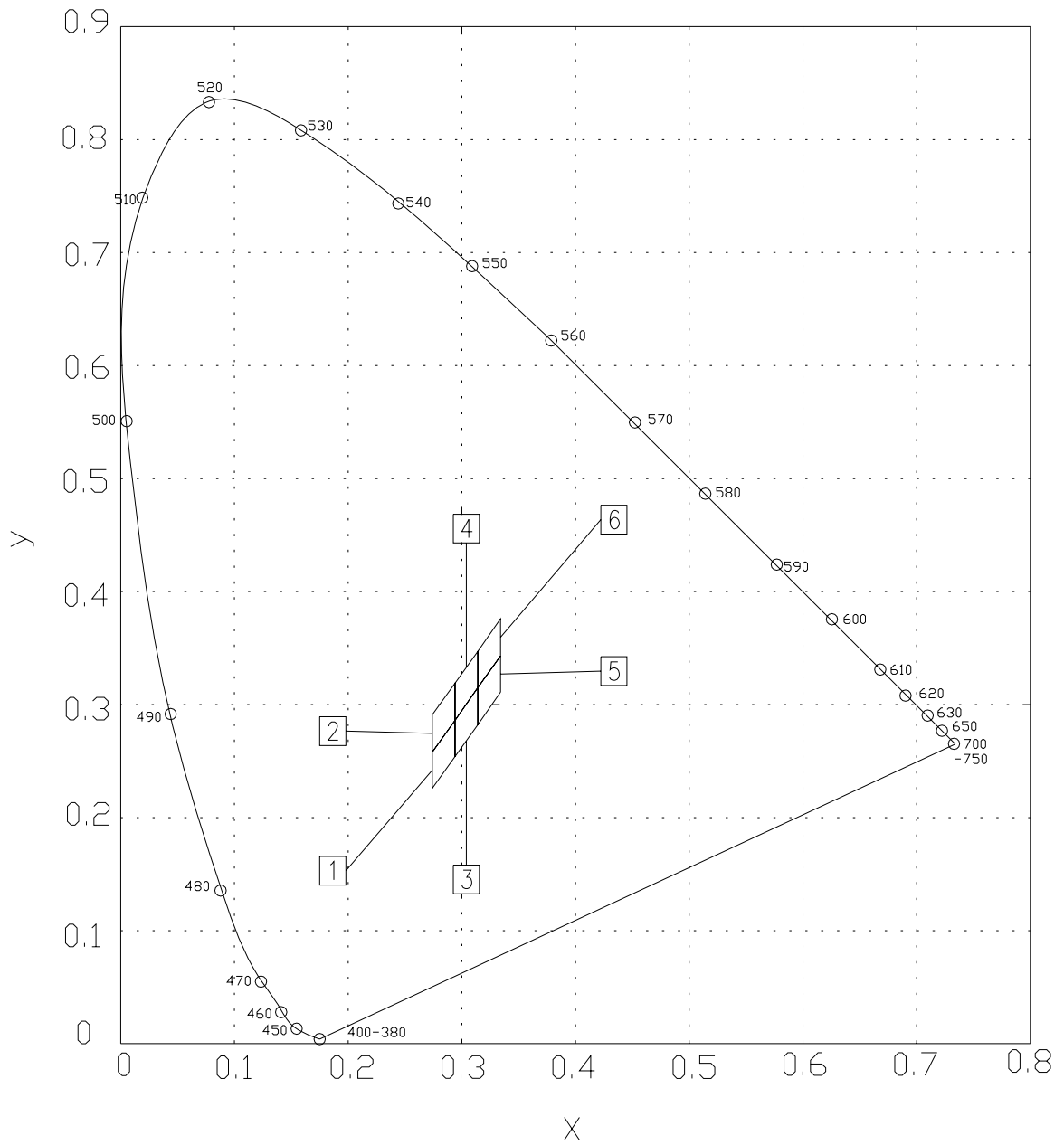
**I<sub>F</sub>= 5mA**

Groups	Bin Code	CIE_x	CIE_y
A	1	0.274	0.226
		0.274	0.258
		0.294	0.286
		0.294	0.254
	2	0.274	0.258
		0.274	0.291
		0.294	0.319
		0.294	0.286
	3	0.294	0.254
		0.294	0.286
		0.314	0.315
		0.314	0.282
	4	0.294	0.286
		0.294	0.319
		0.314	0.347
		0.314	0.315
	5	0.314	0.282
		0.314	0.315
		0.334	0.343
		0.334	0.311
6	0.314	0.315	
	0.314	0.347	
	0.334	0.376	
	0.334	0.343	

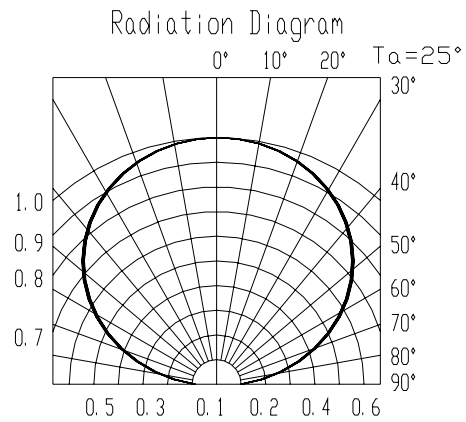
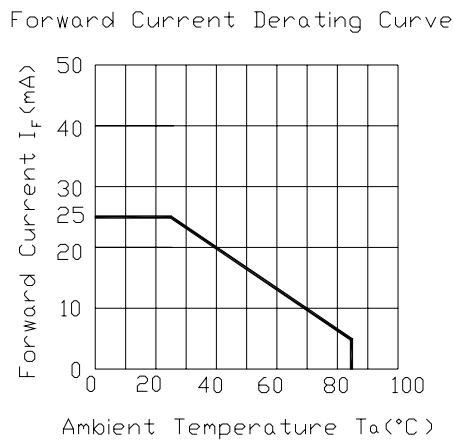
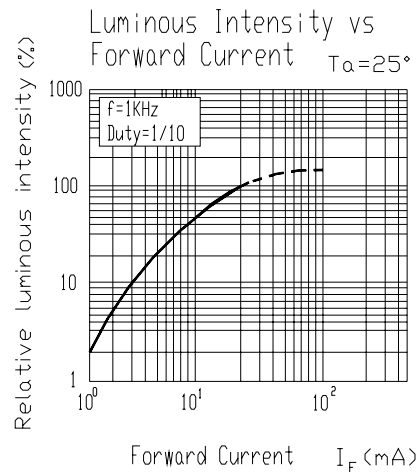
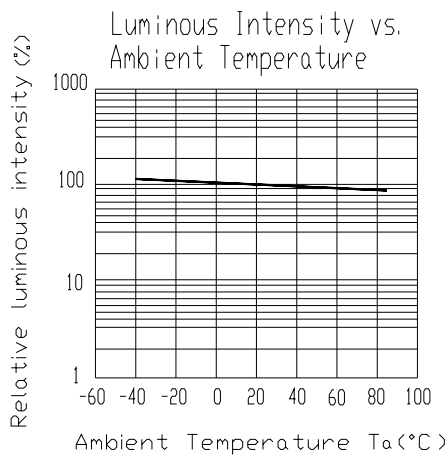
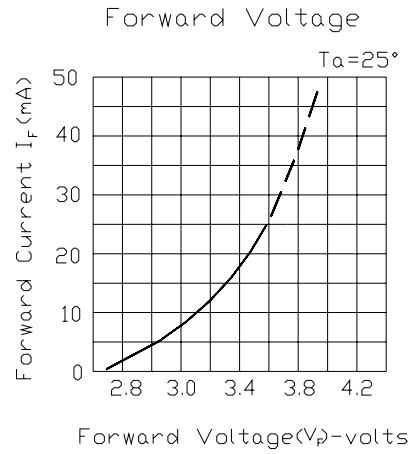
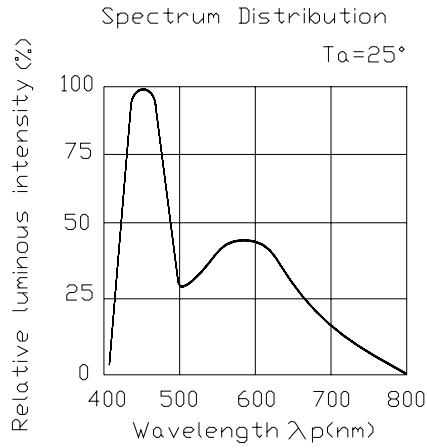
**Notes:**

- 1.The C.I.E. 1931 chromaticity diagram ( Tolerance  $\pm 0.01$ ).
- 2.The products are sensitive to static electricity and care must be fully taken when handling products.

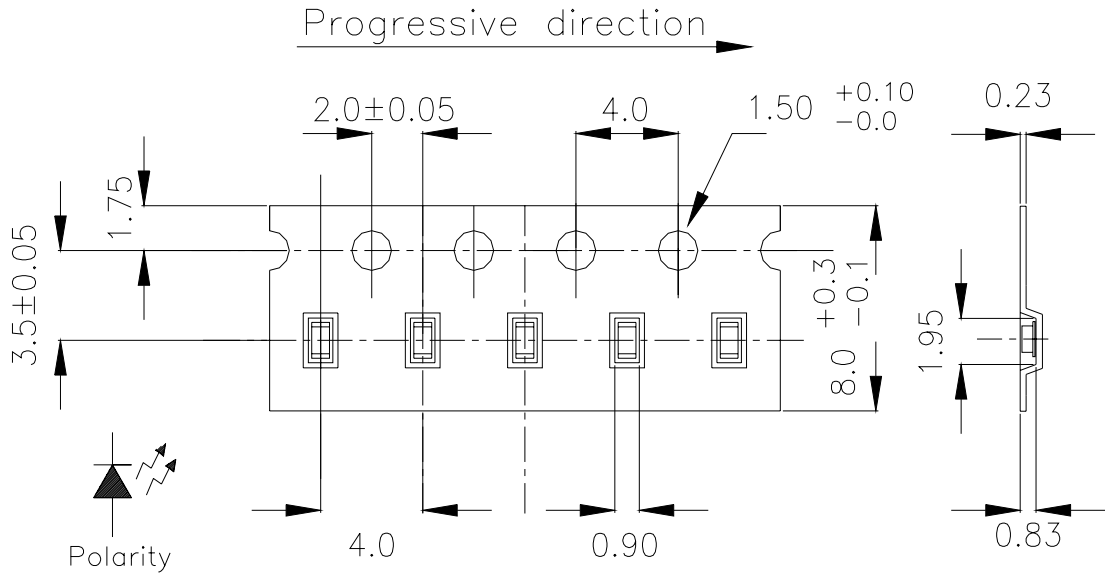
**CIE Chromaticity Diagram**



## Typical Electro-Optical Characteristics Curves

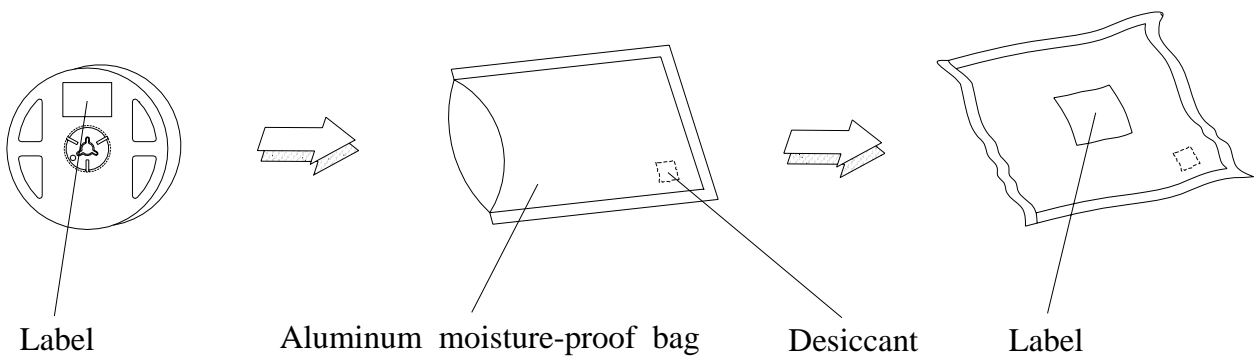


## Carrier Tape Dimensions: Loaded quantity 3000 PCS per reel



**Note:** The tolerances unless mentioned is  $\pm 0.1$ mm , Unit = mm

## Moisture Resistant Packaging





**Reliability Test Items And Conditions**

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C ±5°C Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H : +100°C 15min ∫ 5 min L : -40°C 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : +100°C 5min ∫ 10 sec L : -10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°C	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	I <sub>F</sub> = 5 mA	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C / 85%RH	1000 Hrs.	22 PCS.	0/1

## Precautions For Use

### 1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change ( Burn out will happen ).

### 2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.

2.3 The LEDs should be used within a year.

2.4 After opening the package, the LEDs should be kept at 30°C or less and 70%RH or less.

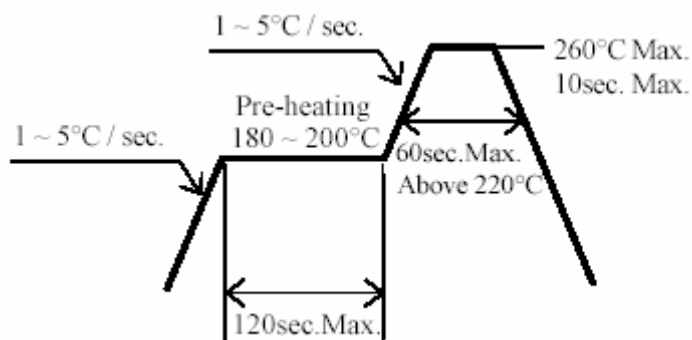
2.5 The LEDs should be used within 168 hours (7 days) after opening the package.

2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 24 hours.

### 3. Soldering Condition

#### 3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

3.4 After soldering, do not warp the circuit board.